



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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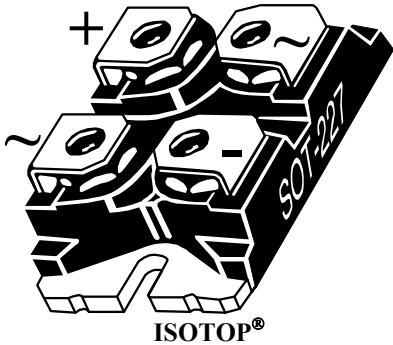
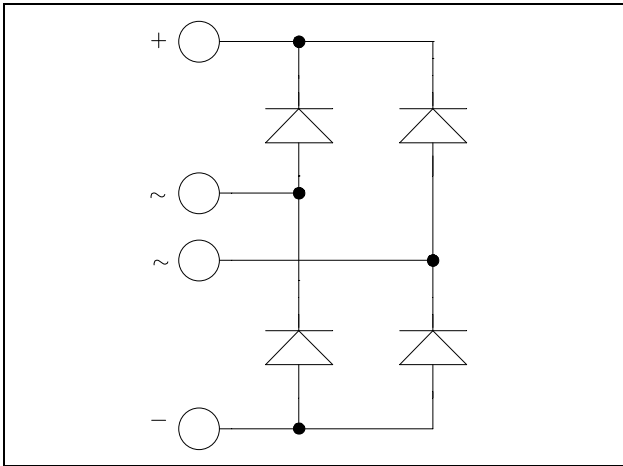
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ISOTOP[®] SiC Diode Full Bridge Power Module

$V_{RRM} = 1200V$
 $I_C = 10A @ T_C = 100^{\circ}C$



Application

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- **SiC Schottky Diode**
 - Zero reverse recovery
 - Zero forward recovery
 - Temperature Independent switching behavior
 - Positive temperature coefficient on VF
- ISOTOP[®] Package (SOT-227)
- Very low stray inductance
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

Absolute maximum ratings

| Symbol | Parameter | Max ratings | Unit |
|-------------|---|-------------|------|
| V_R | Maximum DC reverse Voltage | 1200 | V |
| V_{RRM} | Maximum Peak Repetitive Reverse Voltage | | |
| $I_{F(AV)}$ | Maximum Average Forward Current | 10 | A |
| I_{FSM} | Non-Repetitive Forward Surge Current | 250 | |

Duty cycle = 50% $T_C = 100^{\circ}C$ $T_C = 25^{\circ}C$

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.
 See application note APT0502 on www.microsemi.com

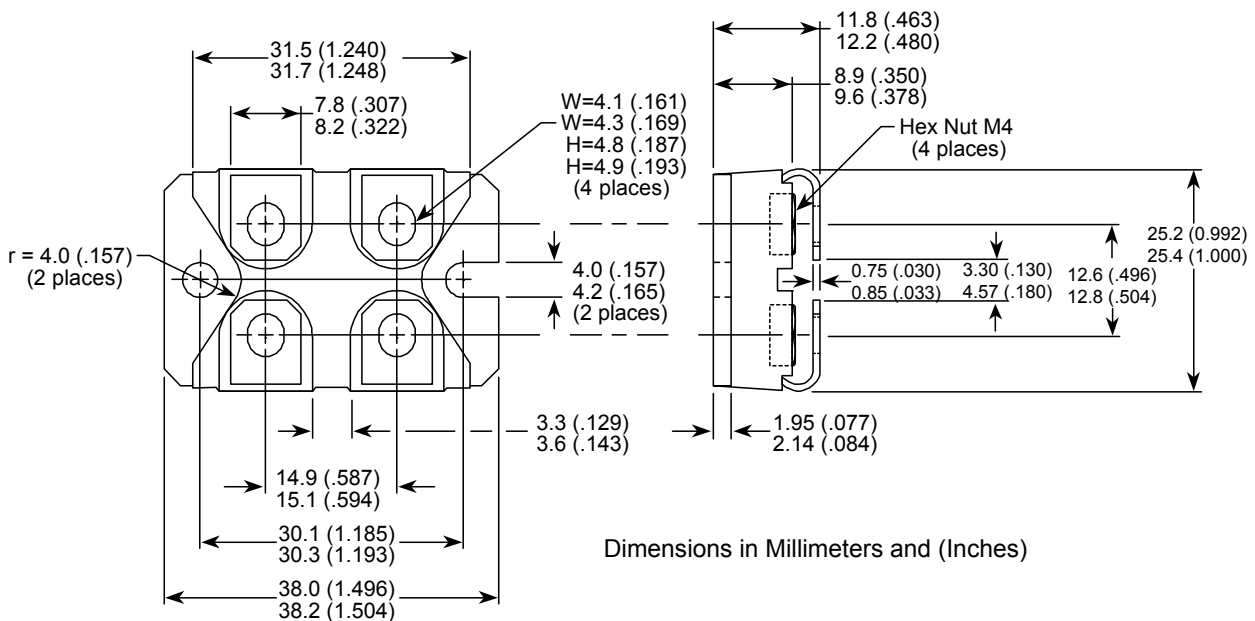
All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

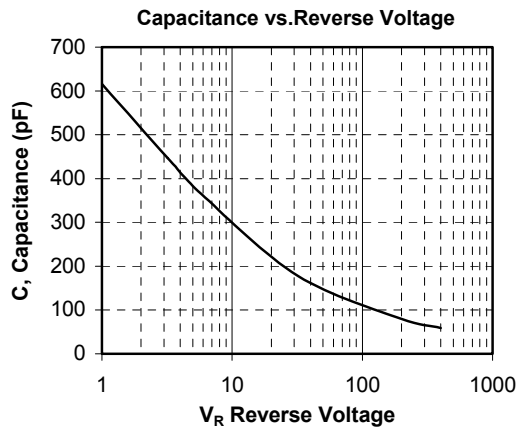
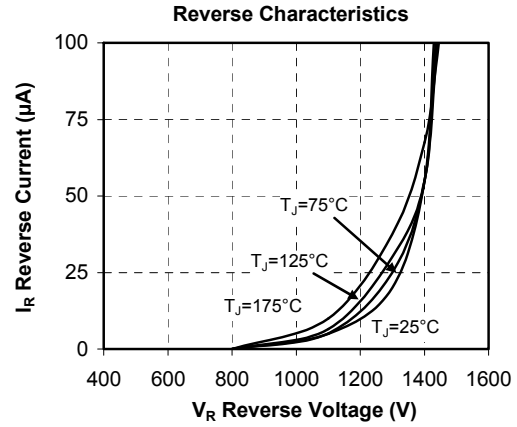
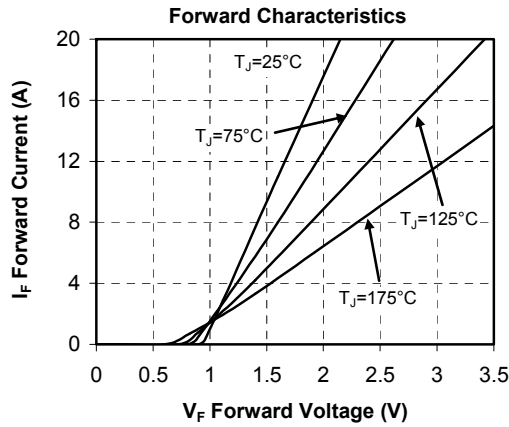
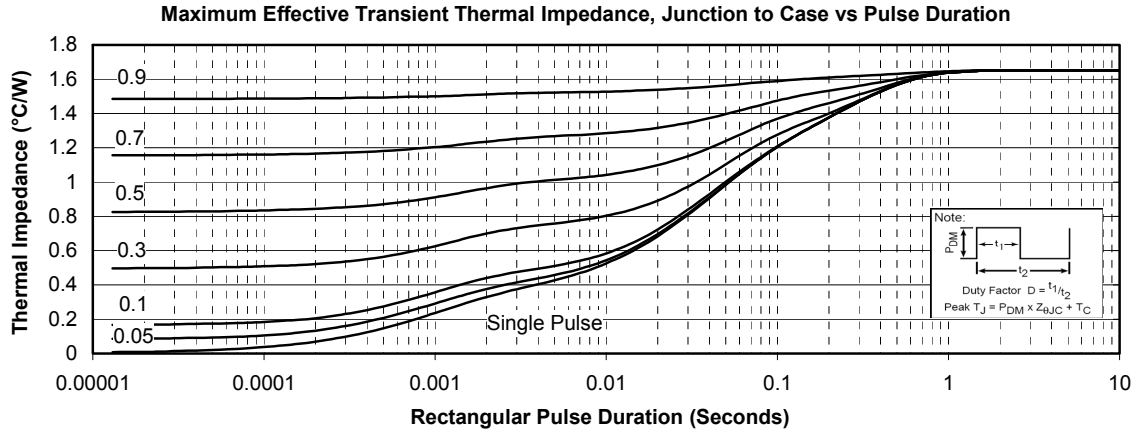
Electrical Characteristics

| Symbol | Characteristic | Test Conditions | Min | Typ | Max | Unit | |
|----------|---------------------------------|--|---------------------------|-----|-----|------|---------------|
| V_F | Diode Forward Voltage | $I_F = 10\text{A}$ | $T_j = 25^\circ\text{C}$ | | 1.6 | 1.8 | V |
| | | | $T_j = 175^\circ\text{C}$ | | 2.3 | 3 | |
| I_{RM} | Maximum Reverse Leakage Current | $V_R = 1200\text{V}$ | $T_j = 25^\circ\text{C}$ | | 32 | 200 | μA |
| | | | $T_j = 175^\circ\text{C}$ | | 56 | 1000 | |
| Q_C | Total Capacitive Charge | $I_F = 10\text{A}, V_R = 600\text{V}$ $di/dt = 500\text{A}/\mu\text{s}$ | | 40 | | nC | |
| C | Total Capacitance | $f = 1\text{MHz}, V_R = 200\text{V}$ | | 96 | | pF | |
| | | $f = 1\text{MHz}, V_R = 400\text{V}$ | | 69 | | | |

Thermal and package characteristics

| Symbol | Characteristic | Min | Typ | Max | Unit |
|----------------|--|------|------|------|---------------------------|
| R_{thJC} | Junction to Case Thermal resistance | | | 1.65 | $^\circ\text{C}/\text{W}$ |
| R_{thJA} | Junction to Ambient | | | 20 | $^\circ\text{C}/\text{W}$ |
| V_{ISOL} | RMS Isolation Voltage, any terminal to case $t = 1$ min, 50/60Hz | 2500 | | | V |
| T_j, T_{STG} | Storage Temperature Range | -55 | | 175 | $^\circ\text{C}$ |
| T_L | Max Lead Temp for Soldering: 0.063" from case for 10 sec | | | 300 | $^\circ\text{C}$ |
| Torque | Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine) | | | 1.5 | N.m |
| Wt | Package Weight | | 29.2 | | g |

SOT-227 (ISOTOP[®]) Package Outline


Typical Performance Curve


ISOTOP® is a registered trademark of ST Microelectronics NV

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